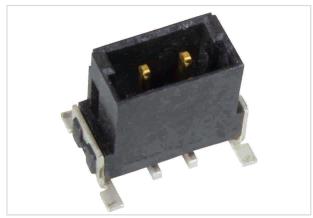


# har-flex Power M str 2P SMT PL1 Sample



| Part number        | 15 52 002 2601 333                        |
|--------------------|---|
| Specification      | har-flex Power M str 2P SMT PL1<br>Sample |
| HARTING eCatalogue | https://b2b.harting.com/15520022601333    |

Image is for illustration purposes only. Please refer to product description.

## Identification

| Category                   | Connectors            |
|----------------------------|-----------------------|
| Series                     | har-flex <sup>®</sup> |
| Identification             | Power                 |
| Element                    | Male connector        |
| Description of the contact | Straight              |

## Version

| Termination method | Reflow soldering termination (SMT)  |
|--------------------|---|
| Connection type    | Motherboard to daughtercard Mezzanine   |
| Number of contacts | 2   |
| Details            | According to IEC 61984, it is an unencapsulated connector. Protection against electric shock must be ensured by the type of installation by the user. |
| Pack contents      | Sample  |

#### Technical characteristics

| Contact spacing (termination side) | 2.54 mm             |
|------------------------------------|---------------------|
| Contact spacing (mating side)      | 2.54 mm             |
| Stacking height                    | 3.25 mm             |
| Rated current                      | 25 A                |
| Rated voltage                      | 180 V               |
| Rated voltage                      | acc. to IEC 60664-1 |
| Rated impulse voltage              | 1.5 kV              |
| Pollution degree                   | 2                   |



## Technical characteristics

| Clearance distance               | ≥1.74 mm                            |
|----------------------------------|-------------------------------------|
| Creepage distance                | ≥1.74 mm PCB<br>≥1.89 mm Connector  |
| Insulation resistance            | >10 <sup>10</sup> Ω                 |
| Contact resistance               | ≤25 mΩ                              |
| Limiting temperature             | -55 +125 °C                         |
| Performance level                | 1                                   |
| Mating cycles                    | ≥500                                |
| Test voltage U <sub>r.m.s.</sub> | 1.39 kV                             |
| Isolation group                  | IIIa (175 ≤ CTI < 400)              |
| Moisture Sensitivity Level (MSL) | 1 acc. to ECA/IPC/JEDEC J-STD-020D  |
| Process Sensitivity Level (PSL)  | R0 acc. to ECA/IPC/JEDEC J-STD-020D |
| Coplanarity of contacts          | 0.1 mm                              |

## Material properties

| Material (insert)                         | Liquid crystal polymer (LCP)                          |
|---|---|
| Colour (insert)                           | Black   |
| Material (contacts)                       | Copper alloy  |
| Surface (contacts)                        | Au over Pd/Ni Mating side Tin plated Termination side |
| Material flammability class acc. to UL 94 | V-0   |

## Commercial data

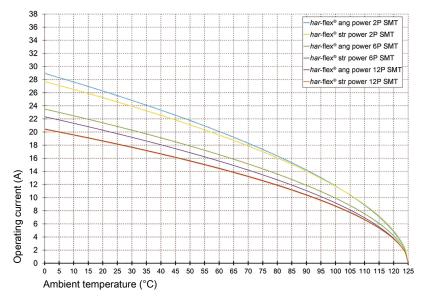
| Packaging size                 | 1  |
|--------------------------------|--|
| Net weight                     | 0.1 g                                    |
| Country of origin              | China                                    |
| European customs tariff number | 85366990                                 |
| eCl@ss                         | 27460201 PCB connector (board connector) |



#### Current carrying capacity

The current carrying capacity of the connectors is limited by the thermal load capability of the contact element material including the connections and the insulating parts. The derating curve is therefore valid for currents which flow constantly (non-intermittent) through each contact element of the connector evenly, without exceeding the allowed maximum temperature.

Measuring and testing techniques acc. to IEC 60512-5-2



Derating curve 80%